

SOT1780-5

WLCSP36, wafer level chip-scale package; 36 bumps; 0.4 mm pitch, 2.62 mm x 2.51 mm x 0.5 mm body

22 March 2020

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP36
Package type industry code	WLCSP36
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	08-12-2017
Manufacturer package code	98ASA01159D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.59	2.62	2.65	mm
package width	2.48	2.51	2.54	mm
seated height	-	0.5	0.54	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	36	-	



2 Package outline

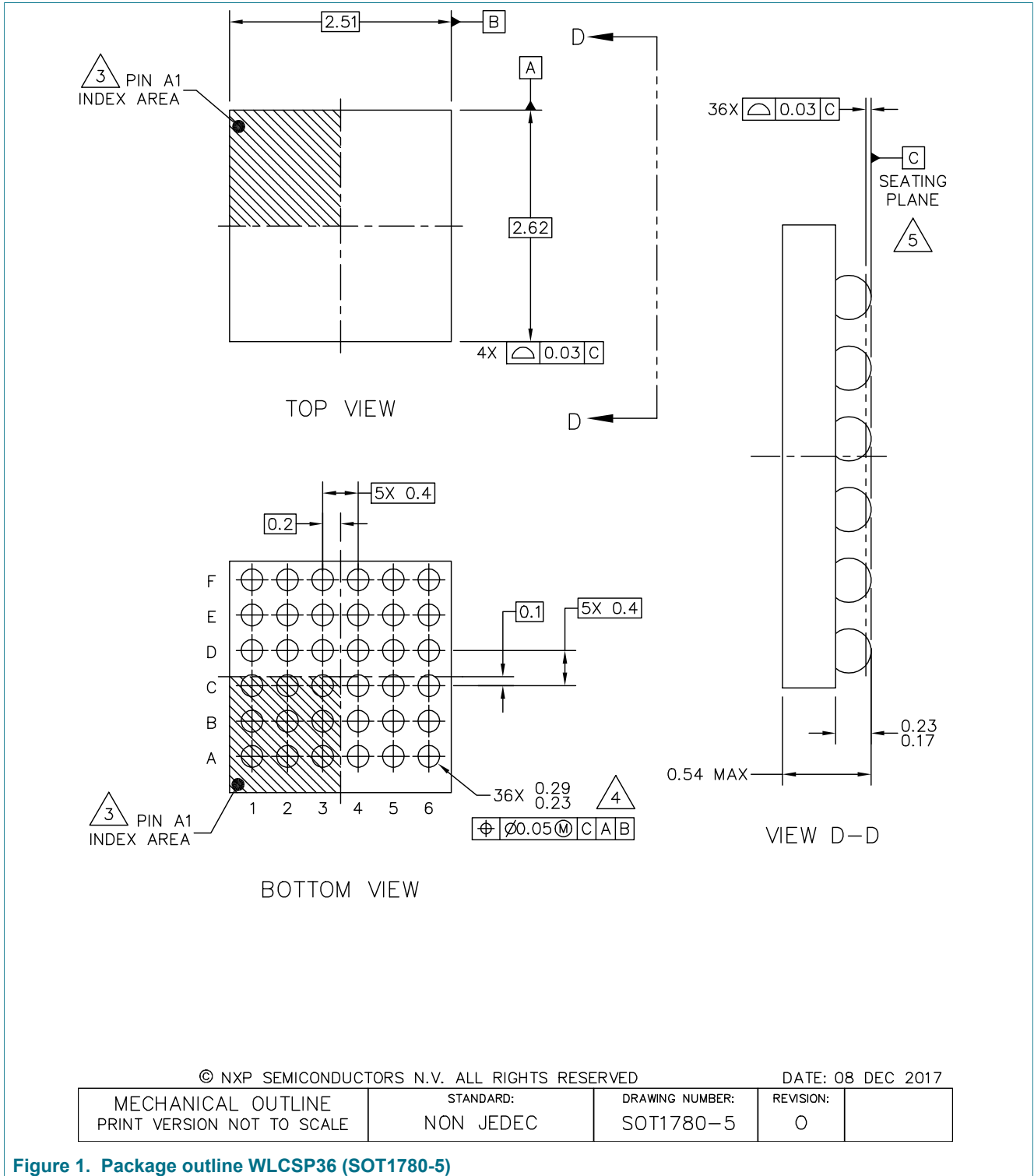


Figure 1. Package outline WLCSP36 (SOT1780-5)

3 Soldering

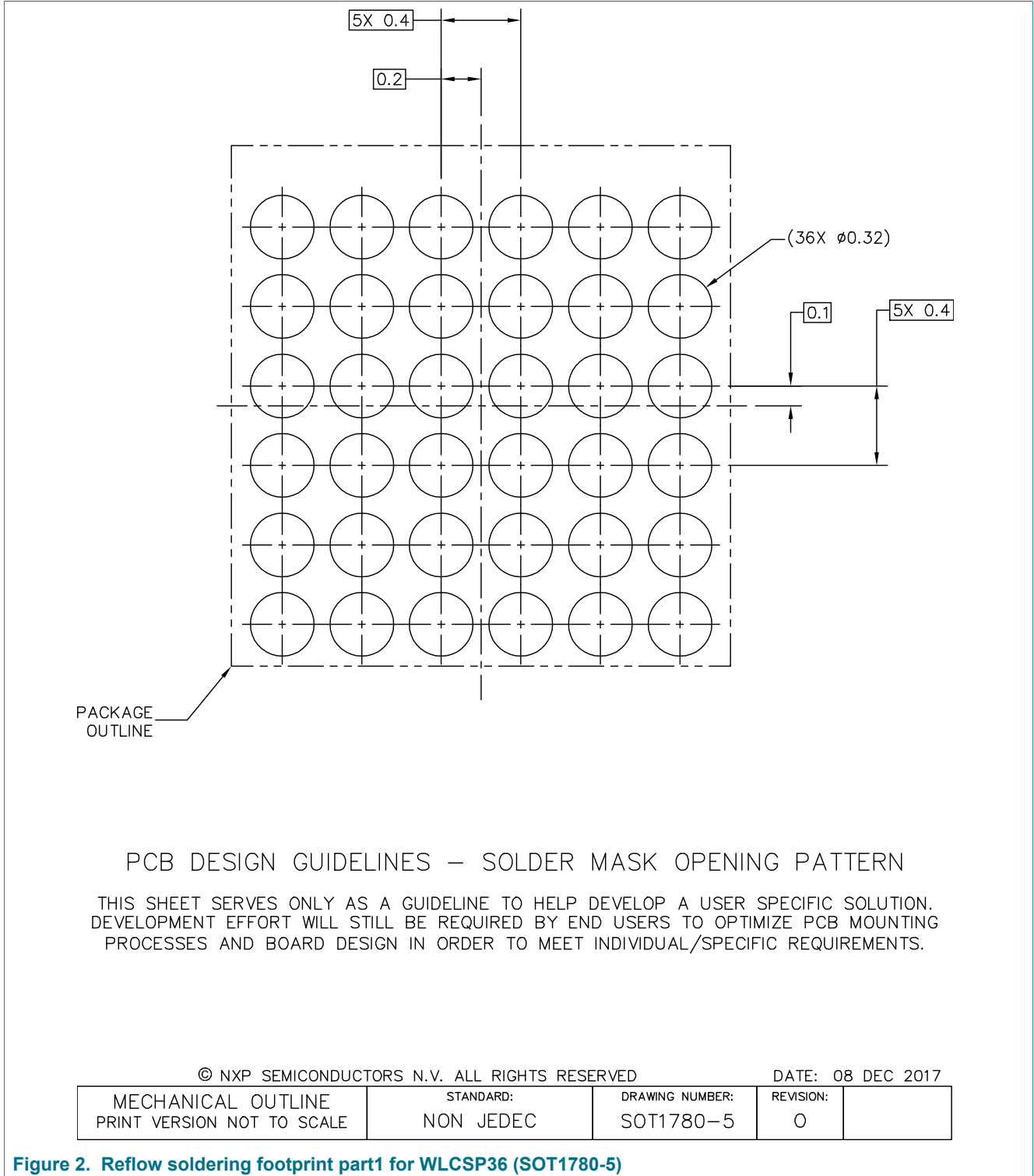


Figure 2. Reflow soldering footprint part1 for WLCSP36 (SOT1780-5)

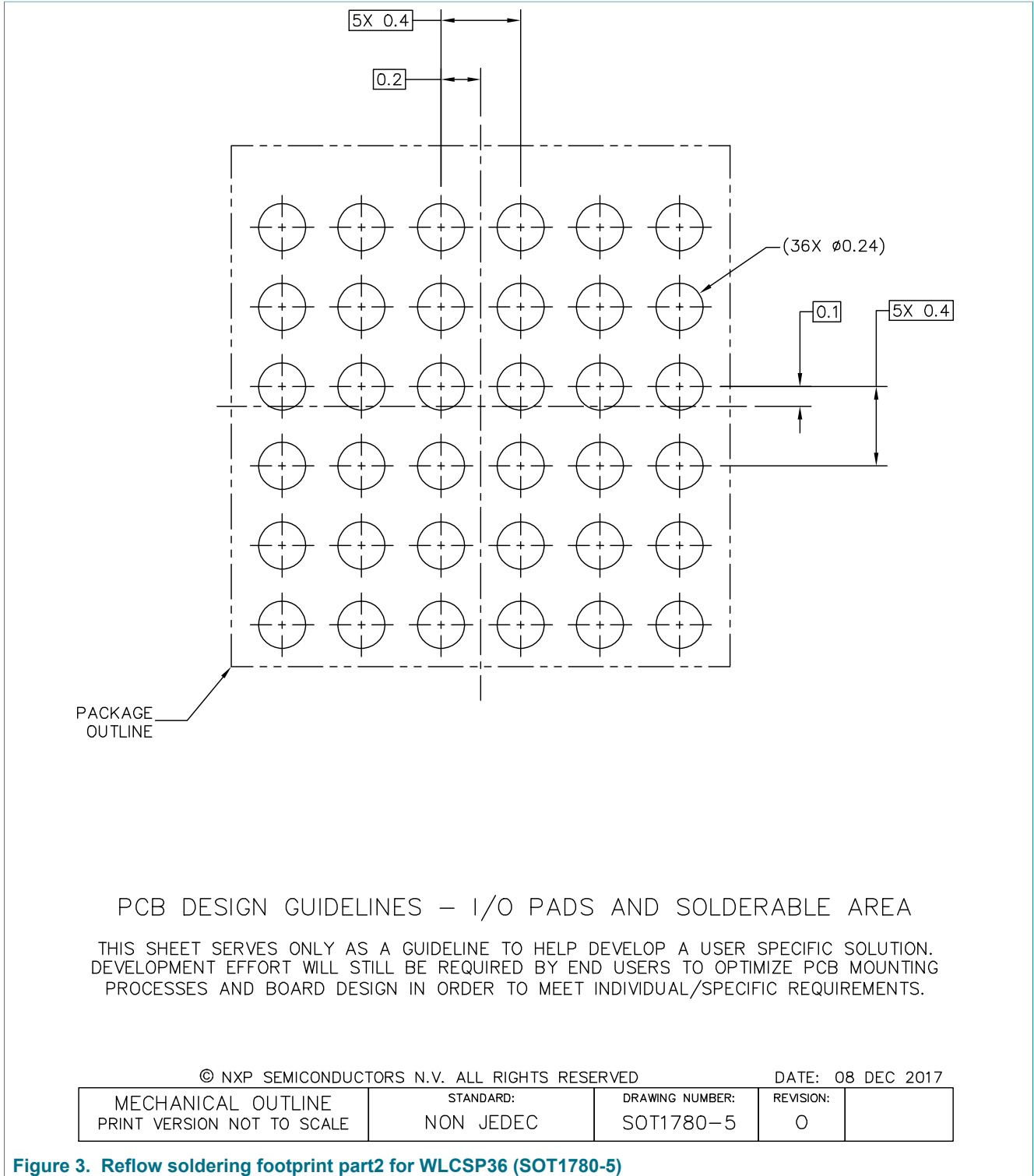


Figure 3. Reflow soldering footprint part2 for WLCSP36 (SOT1780-5)

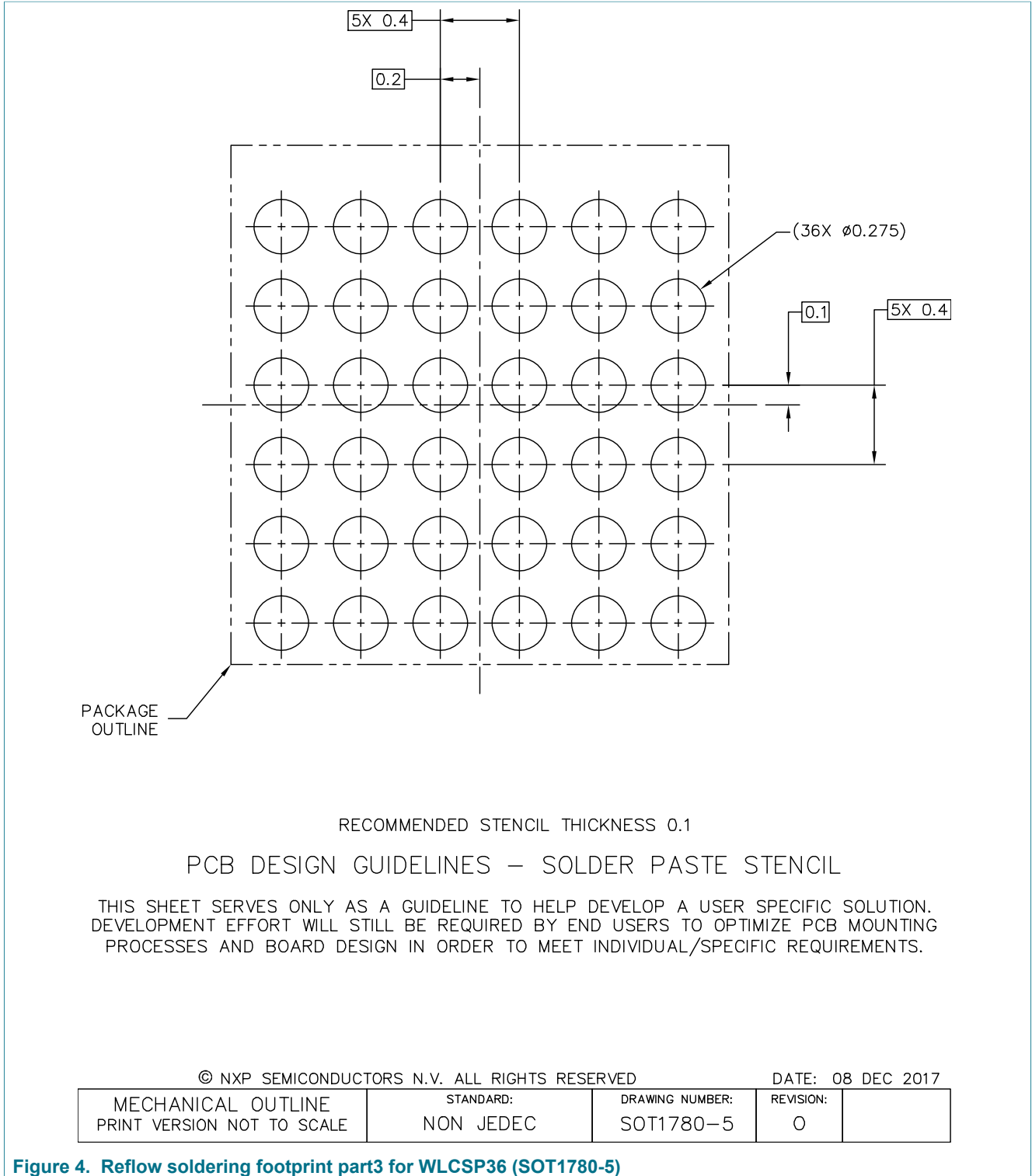


Figure 4. Reflow soldering footprint part3 for WLCSP36 (SOT1780-5)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1780-5	REVISION: 0	
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Figure 5. Package outline note WLCSP36 (SOT1780-5)

4 Legal information

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